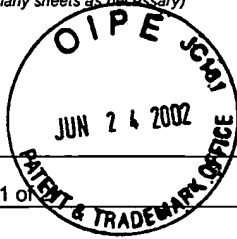


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Application Number	09/944983
Filing Date	August 30, 2001
First Named Inventor	Farrar, Paul
Group Art Unit	Unknown
Examiner Name	Unknown

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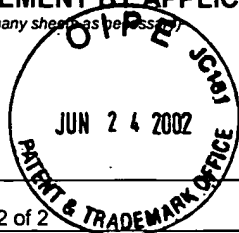
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Group Art Unit	Unknown
Examiner Name	Unknown

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